

Title (en)

METHOD FOR JOINING A SILICON PLATE TO ANOTHER PLATE

Title (de)

VERFAHREN ZUR VERBINDUNG EINER SILIZIUMPLATTE MIT EINER WEITEREN PLATTE

Title (fr)

PROCEDE DESTINE A RELIER UNE PLAQUE DE SILICIUM A UNE AUTRE PLAQUE

Publication

EP 1436830 A1 20040714 (DE)

Application

EP 02769904 A 20020905

Priority

- DE 0203282 W 20020905
- DE 10149140 A 20011005

Abstract (en)

[origin: WO03032377A1] Disclosed is a method for joining a silicon plate (1) to another plate (2), wherein the laser beam is directed through the silicon plate (1) to the other plate (2). The wavelength of the laser beam is selected in such a way that only a negligibly small amount of energy is absorbed in the silicon plate (1). The energy of the laser beam is used to melt a highly absorbent material which subsequently produces a connection between the silicon plate (1) and the other plate (2).

IPC 1-7

H01L 21/20; **H01L 21/60**

IPC 8 full level

B29C 65/16 (2006.01); **B29C 65/60** (2006.01); **B81C 1/00** (2006.01); **H01L 21/20** (2006.01); **H01L 21/60** (2006.01); **H01L 21/762** (2006.01); **H01L 21/58** (2006.01)

CPC (source: EP US)

B29C 65/1635 (2013.01 - EP US); **B29C 65/1683** (2013.01 - EP US); **B29C 65/608** (2013.01 - EP US); **B29C 66/1122** (2013.01 - EP US); **B29C 66/12421** (2013.01 - EP US); **B29C 66/472** (2013.01 - EP US); **B29C 66/53461** (2013.01 - EP US); **B29C 66/71** (2013.01 - EP US); **B81C 1/00269** (2013.01 - EP US); **B81C 1/00357** (2013.01 - EP US); **H01L 21/2007** (2013.01 - EP US); **H01L 21/76251** (2013.01 - EP US); **H01L 24/83** (2013.01 - EP US); **B29C 65/1612** (2013.01 - EP US); **B29C 66/712** (2013.01 - EP US); **B29C 66/7392** (2013.01 - EP US); **B29K 2083/00** (2013.01 - EP US); **B29L 2031/756** (2013.01 - EP US); **B81C 2201/019** (2013.01 - EP US); **B81C 2203/019** (2013.01 - EP US); **H01L 2224/80224** (2013.01 - EP US); **H01L 2224/80365** (2013.01 - EP US); **H01L 2224/80379** (2013.01 - EP US); **H01L 2224/804** (2013.01 - EP US); **H01L 2224/80488** (2013.01 - EP US); **H01L 2224/83224** (2013.01 - EP US); **H01L 2224/834** (2013.01 - EP US); **H01L 2224/83424** (2013.01 - EP US); **H01L 2224/83447** (2013.01 - EP US); **H01L 2224/83466** (2013.01 - EP US); **H01L 2224/83471** (2013.01 - EP US); **H01L 2224/83487** (2013.01 - EP US); **H01L 2224/8349** (2013.01 - EP US); **H01L 2224/83801** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/09701** (2013.01 - EP US); **H01L 2924/12042** (2013.01 - EP US)

Citation (search report)

See references of WO 03032377A1

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Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR IE IT LI LU MC NL PT SE SK TR

DOCDB simple family (publication)

WO 03032377 A1 20030417; DE 10149140 A1 20030417; EP 1436830 A1 20040714; US 2004082145 A1 20040429; US 6955975 B2 20051018

DOCDB simple family (application)

DE 0203282 W 20020905; DE 10149140 A 20011005; EP 02769904 A 20020905; US 43352503 A 20031113